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Prohibited US Person Activities

- Shipping, transmitting, or transferring (in-country) to or within the PRC any item not subject to the EAR that the U.S. Person knows will be used in the “development” or “production” of integrated circuits at a semiconductor fabrication “facility” located in the PRC that fabricates ICs meeting any of the following criteria:
    - (A)Logic integrated circuits using a non-planar architecture or with a “production” technology node of 16/14 nanometers or less;
    - (B) NOT-AND (NAND) memory integrated circuits with 128 layers or more; or
    - (C) Dynamic random-access memory (DRAM) integrated circuits using a “production” technology node of 18 nanometer half-pitch or less; or
- Facilitating the shipment, transmission, or transfer (in-country), or servicing any item not subject to the EAR that the U.S. Person knows will be used in the “development” or “production” of ICs at a PRC facility that also fabricates the above ICs;
- Shipping, transmitting, transferring (in-country) to or within the PRC any item not subject to the EAR and meeting the parameters of any ECCN in Product Groups B, C, D, or E in Category 3 of the CCL that the U.S. person knows will be used in the “development” or “production” of ICs at any semiconductor facility in the PRC, but the U.S. person does not know whether such semiconductor fabrication facility fabricates the above ICs;
- Facilitating the shipment, transmission, or transfer (in-country) to or within the PRC of any item not subject to the EAR and meeting the parameters of any ECCN in Product Groups B, C, D, or E in Category 3 of the CCL that the U.S. Person knows will be used in the “development” or “production,” of integrated circuits at any semiconductor fabrication “facility” located in the PRC, but the U.S. Person does not know whether such semiconductor fabrication “facility” fabricates the above ICs;
- Servicing any item not subject to the EAR and meeting the parameters of any ECCN in Product Groups B, C, D, or E in Category 3 of the CCL that the U.S. Person knows will be used in the “development” or “production” of integrated circuits at any semiconductor fabrication “facility” located in the PRC, but the U.S. Person does not know whether such semiconductor fabrication “facility” fabricates the above ICs;
- Shipping, transmitting, or transferring (in-country) to or within the PRC any item not subject to the EAR and meeting the parameters of ECCN 3B090, 3D001 (for 3B090), or 3E001 (for 3B090) regardless of end use or end user;
- Facilitating the shipment, transmission, or transfer (in-country) to or within the PRC of any item not subject to the EAR and meeting the parameters of ECCN 3B090, 3D001 (for 3B090), or 3E001 (for 3B090), regardless of end use or end user; or
- Servicing any item not subject to the EAR located in the PRC and meeting the parameters of ECCN 3B090, 3D001 (for 3B090), or 3E001 (for 3B090), regardless of end use or end user.